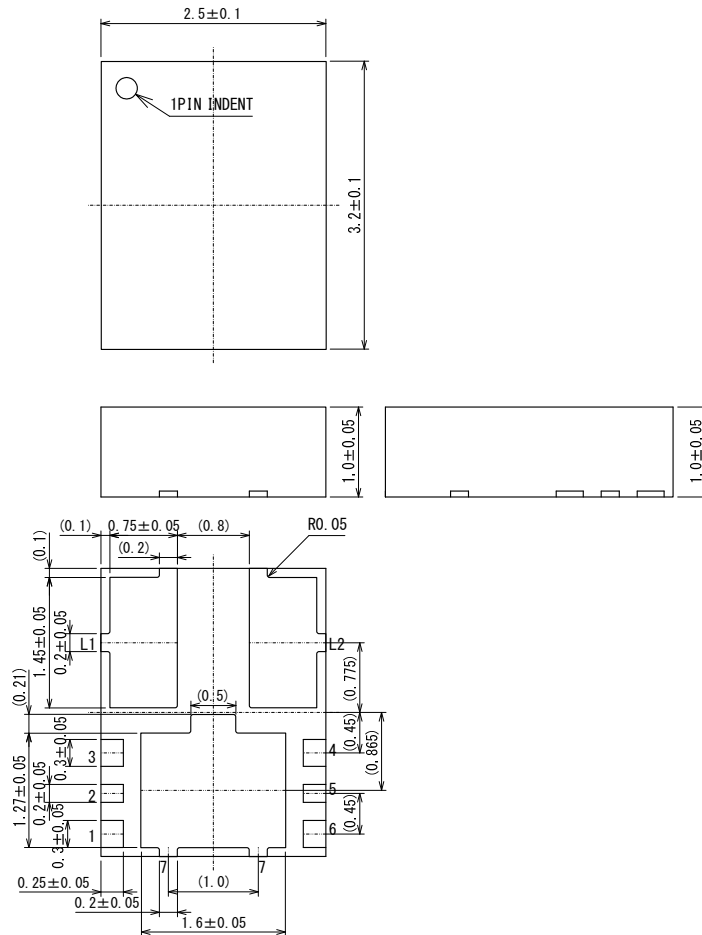


外形寸法図 Packaging Information /
参考パターン寸法 Reference Pattern Layout Dimensions

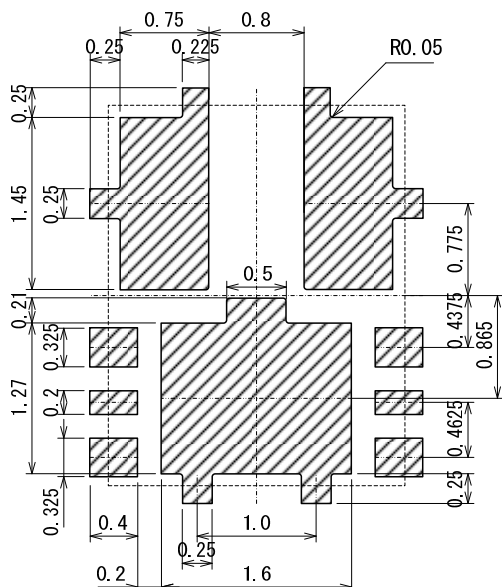
USP-9B01

Unit: mm

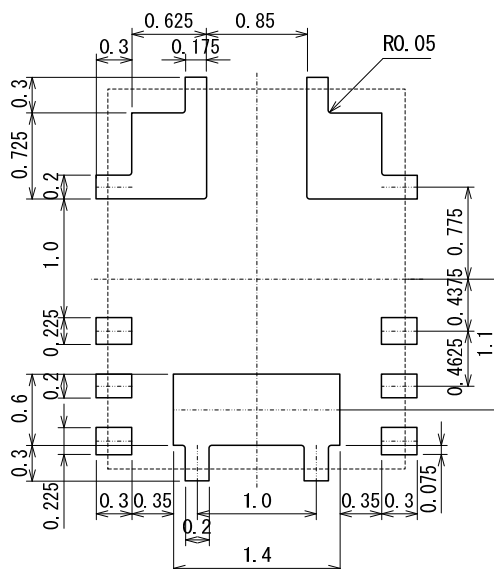
●外形寸法図 / Packaging Information



●参考パターンレイアウト /
Reference pattern layout



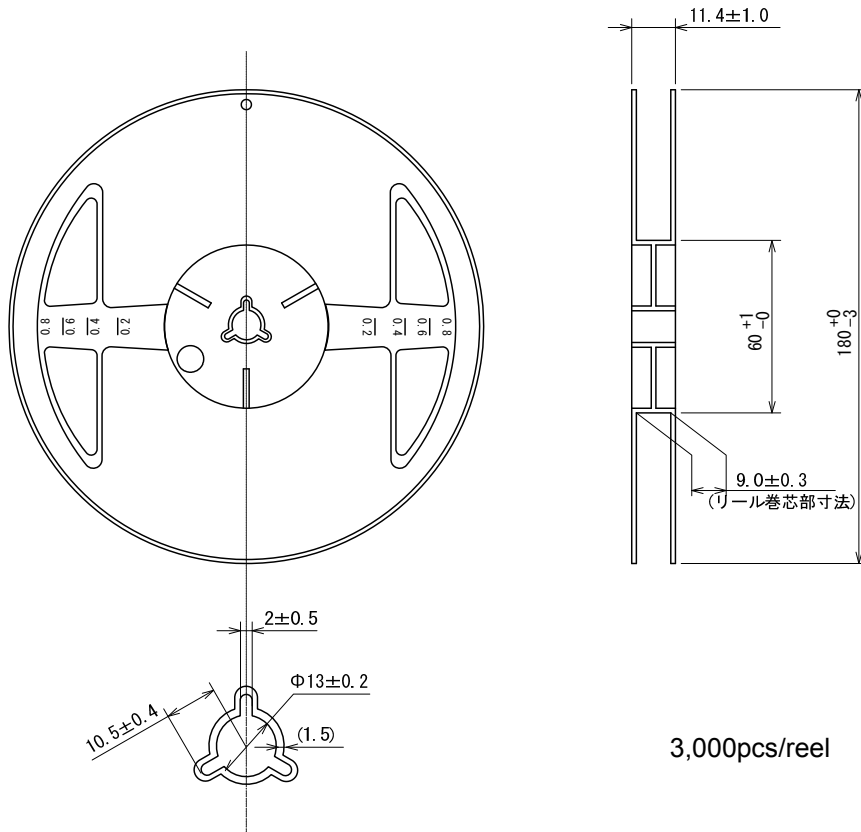
●参考メタルマスクデザイン /
Reference metal mask design



テーピング仕様 / Taping Specifications

USP-9B01

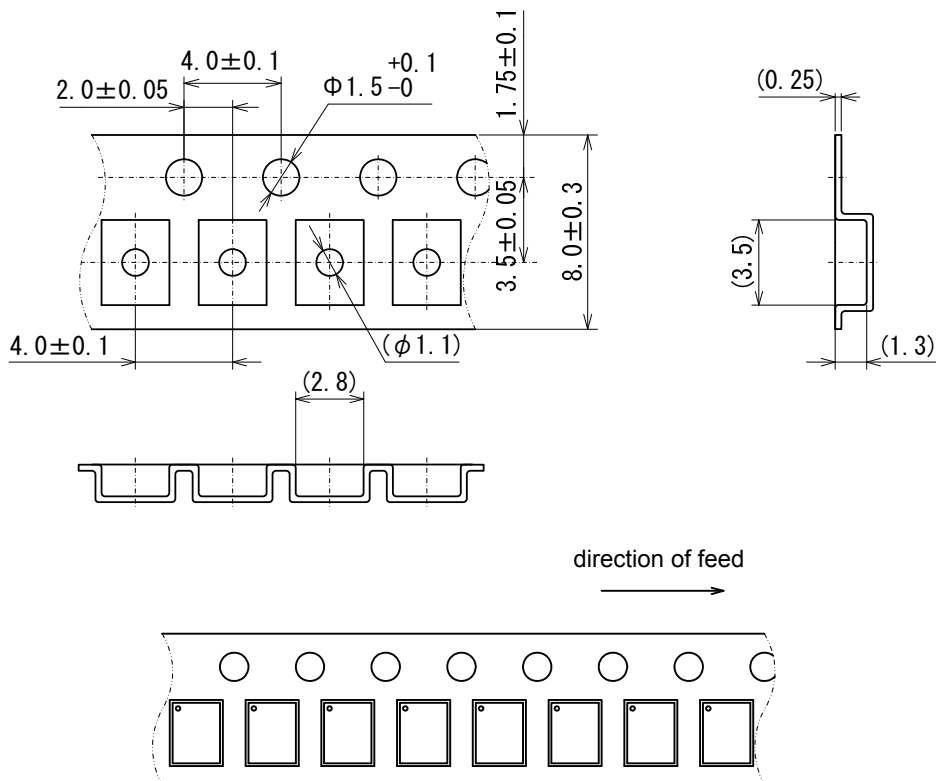
●リール/Reel



Unit: mm

3,000pcs/reel

●テーピング仕様/Taping Specifications

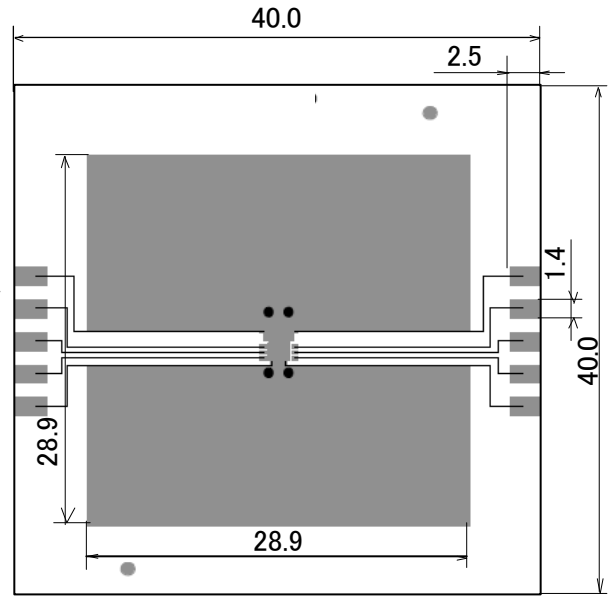


USP-9B01 Power Dissipation

Power dissipation data for the USP-9B01 is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40mm×40mm (1600mm² in one side)
- Copper (Cu) traces occupy 50% of the board area in top and back faces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6mm
- Through-hole: 4 x 0.8 Diameter

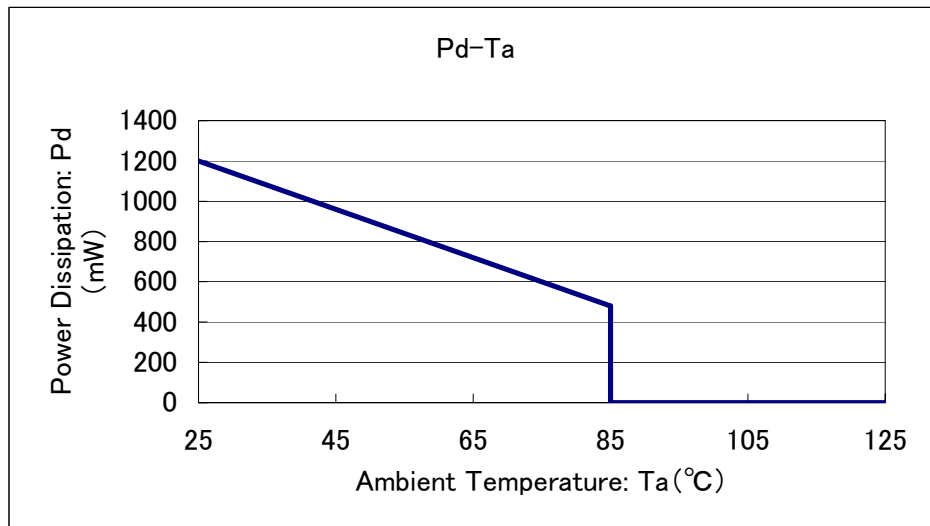


Evaluation Board (unit: mm)

2. Power Dissipation vs. Ambient temperature (85°C)

Board Mount ($T_{jmax} = 125^{\circ}\text{C}$)

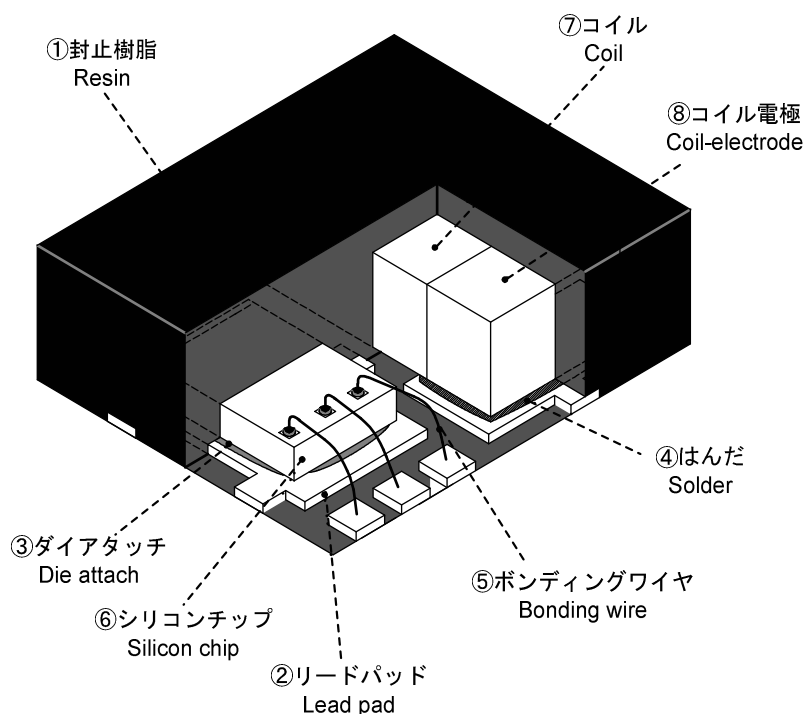
Ambient Temperature(°C)	Power Dissipation Pd (mW)	Thermal Resistance(°C/W)
25	1200	83.33
85	480	



USP-9B01構造図

USP-9B01 Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	
端子処理 Outer pad plating	Auメッキ Gold plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ はんだ Solder	鉛フリーはんだ Pb-free solder	Sn95Sb5
⑤ ボンディングワイヤ Bonding wire	Au	
⑥ シリコンチップ Silicon chip	Si	
⑦ コイル Coil	セラミック Ceramic	
⑧ コイル電極 Coil-Electrode	Ni 下地めっき + Snめっき Ni pre-plating + Sn plating	

捺印表示 Marking	レーザー Laser marking
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